

semiconductor packaging news

EV Group Expands Collaboration with ITRI on Heterogeneous Integration Process Development – September 2, 2022

semiconductor packaging news

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September 2, 2022

Why Arm's Lawsuit Against Qualcomm is a Big Deal

Arm is suing Qualcomm, putting two of the most valuable semiconductor firms into direct conflict, and raising questions about the future of the partnership between the two firms. The lawsuit, filed on Wednesday in the U.S. District Court for the District of Delaware, comes at a critical time for Arm as its owner Softbank hopes to soon list the firm on public markets after a deal to sell ...
CNBC



2x Faster, 1/2 the Capital Cost, 1/2 the Footprint

Looking for revolutionary productivity for your advanced technologies? YES Plasma Resist/Descum Systems have high throughput & strip rate.
Yield Engineering Systems, Inc.



Do thin wafers have you frazzled?

Our new ADJUST-A-VAC allows you to reduce the vacuum pressure from just below atmospheric pressure to up to ten inches of mercury. A LED bar display shows the vacuum level.
Virtual Industries, Inc.



OSATs strive to grow revenues from automotive sector

Taiwan-based OSATs including ASE Technology, Powertech Technology Group (PTI), King Yuan Electronics (KYE), Ardentec, Sigurd Microelectronics are all looking to grow ...
Digitimes

The Great Debate: Ball Bonding vs Wedge Bonding

Over the years, microelectronic wire bond process and packaging engineers have debated whether to use ball or wedge bond technologies. This article will focus on the ...
Technical Paper

Securing The Semiconductor Supply Chain With Secure Provisioning

The level of awareness of supply chain risks is rising and threats are being seen on many fronts. The Semiconductor Industry Association has reported instances ...
Semiconductor Engineering

Technical Papers

- [Effects of Long-Term Storage on Mechanical and Electrical Integrity](#)
- [The Great Debate: Ball Bonding vs Wedge Bonding](#)
- [Chip-Last HDFO Interposer-PoP](#)
- [Air Gap, Buried Layer and Micro-Channel Measurement](#)
- [Essential Practices for Gold Mitigation of Electronic Components](#)
- [The Journey to Full-Scale Semiconductor Packaging Manufacturing](#)
- [Dispositioning Hermetic Microelectronic Components With High Internal Moisture](#)

Amkor's Double Sided Molded BGA Solutions

To improve the integration of RFFE solutions, Amkor offers a DSMBGA package that allows molded assembly of components on both sides of the substrate.
Amkor Technology, Inc.



5G Antennas in the EMC

Miniaturization requires using available package real estate to achieve functional requirements. New liquid encapsulants are enabling direct structuring of 5G mmWave antennas. Find out how.
Henkel Corporation



Micro Dispensing Technology White Paper

The trend toward micro-dispensing technology increases as electronic assembly's shrink & component packages decrease in size.
DL Technology



Today's Sponsor



Test Your Knowledge

Which country is not in the same time zone as Italy: France, Germany, Libya, Greece
See answer below.

Non-Surface Approach For Device Flip

Not all wafer level packages can be sorted, picked, flipped and re-packaged using traditional vacuum tip technology. Non-surface contact handling can be effective, precise & fully automated
Royce Instruments



Press Releases

EV Group Expands Collaboration with ITRI on Heterogeneous Integration Process Development

EV Group (EVG) announced that it has expanded its collaboration with the Industrial Technology Research Institute (ITRI), one of the world's leading applied technology ...
EV Group

Indium Corporation Experts to Present at IMAPS 2022

Three Indium Corporation experts will share their industry knowledge and expertise during four presentations at the 55th International Symposium on Microelectronics (IMAPS) ...
Indium Corporation

Supply Tightening Expected for Specialty Electronic Gases

TECHCET reports that the supply of Specialty Gases, nitrogen trifluoride (NF3) and tungsten hexafluoride (WF6) for electronics could tighten amongst high projected demand ...
TECHCET

Diamond's thermal management properties enable higher performance

A collaboration between Univ. of Bristol and Element Six is accelerating diamond's path



[Nvidia says U.S. government allows A.I. chip development in China](#)

Nvidia on Thursday said the U.S. government will allow it to continue developing its H100 artificial intelligence chip in China. It's a win for the company after it warned that ...
CNBC

[CHIPS Act to have little effect outside US, experts say](#)

US President Joe Biden signing the Creating Helpful Incentives to Produce Semiconductors (CHIPS) and Science Act would have little bearing on individual countries' ...
Taipei Times

[Tech war: US tightens export rules with ban on Nvidia, AMD selling advanced AI chips to China](#)

The US ban on Nvidia and AMD selling some advanced chips to China is set to crimp the ability of Chinese tech companies in areas such as facial recognition and data centres ...
South China Morning Post



[What's Really Behind The Adoption Of EFPGA?](#)

System companies are taking a more proactive role in co-designing their hardware and software roadmaps, so it's no surprise that they are also driving the adoption ...
Semiconductor Engineering

[Design For Security Now Essential For Chips, Systems](#)

It's nearly impossible to create a completely secure chip or system, but much can be done to raise the level of confidence about that security. In the past, security was ...
Semiconductor Engineering

[Chinese smartphone vendors moving away from low-end market even without India's ban](#)

Amid rumors about India's intention to restrict China-based smartphone vendors' presence in the low-end market and repeated denial from Indian government officials, ...
Digitimes


Automatic bench-top die attach system
MAT6200, a unique configuration delivers high accuracy and unmatched versatility for wide range of cold and heated processes using the same platform. User friendly PC GUI.
MicroAssembly Technologies



Wafer Processing Adhesives & Solution
Thin semiconductor chips are common. Backgrinding & thinning process is considered separate, the ability to combine wafer backgrinding-thinning & back-side active buildup improves throughput.
A.I. Technology, Inc.



accelerating diamond's path towards unlocking highly efficient thermal management solutions.
Element Six




Quote of the Day

"Self-confidence is the first requisite to great undertakings."

Samuel Johnson


Optimizing cycle times with Openair-Plasma

Plasma surface treatment has uses in semiconductor manufacturing, such as wire bonding, die bonding, thermal compress bonding, and pre-molding.
Plasmatreat GmbH



Advanced Assembly, Fast


Let us meet your advanced development needs – from COB, MCM and SiP, to flip chip, stacked die and chiplets – in as little as 8 hours. Contact us to learn more.
QP Technologies



What Year Was It?


[First ATM Opens for Business](#)

America's first automatic teller machine (ATM) makes its public debut, dispensing cash to customers at Chemical Bank in Rockville Center, New York.
The day was Sep 2. What year was it?



Bonder for high-density interconnects

The universal SUSS XBS300 Hybrid Bonding Platform allows for fully automated W2W (wafer-to-wafer) and collective D2W (die-to-wafer) hybrid bonding. Learn more.
SUSS MicroTec



Eliminate Gold Embrittlement!

We use automated robotic hot solder dip equipment for gold mitigation on SMT & through-hole devices. Gold plating is removed and replaced with tin-lead solder. Learn more.
Circuit Technology Center



[DDR5 prices to approach sweet spot](#)

DDR5 contract prices, which fell as much as 20% in July alone, are expected to continue trending downward through the end of this year, according to sources at memory ...
Digitimes



X-ray inspection in SMT, semiconductors and labs

See you at electronica.

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Heraeus Electronics

Smart choice for memory devices & smartcards

AgCoat Prime



Is IPA the best choice?

KYZEN offers safe, affordable alternatives that work!

KYZEN 3D
Wafer Backgrinding and Core Coverage | TBA03

Cartoon of the Day



"It's not just you. We're all insecure in one way or another."

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MRS™ Sensor for Challenging Measurement & Inspection

3D High precision optical sensor. Inspect shiny or mirror-like surfaces with sub-micrometer accuracy for features as small as 25µm.

CyberOptics Corporation



Test Your Knowledge Answer

Which country is not in the same time zone as Italy: France, Germany, Libya, Greece
Answer: Greece (1 hour ahead)

NEWSLETTER ARCHIVES

Calendar

- [Sep 6, 2022: MEMS & Imaging Sensors Summit](#)
- [Sep 12, 2022: Overview of semiconductor manufacturing](#)
- [Sep 14, 2022: SEMICON Taiwan](#)
- [Sep 14, 2022: Intro to Semiconductor Design & Fabrication Webinar for American Attendees](#)

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Wafer Processing Adhesives & Solution

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